

Features

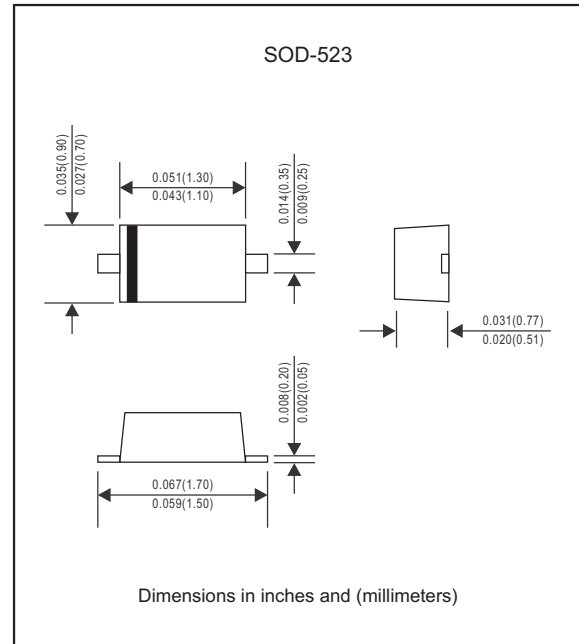


- Small package
- Low reverse current
- Fast switching speed
- Surface mount package ideally suited for automatic insertion
- Lead-free parts meet RoHS requirements
- Compliant to Halogen-free.

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-523
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

Package outline



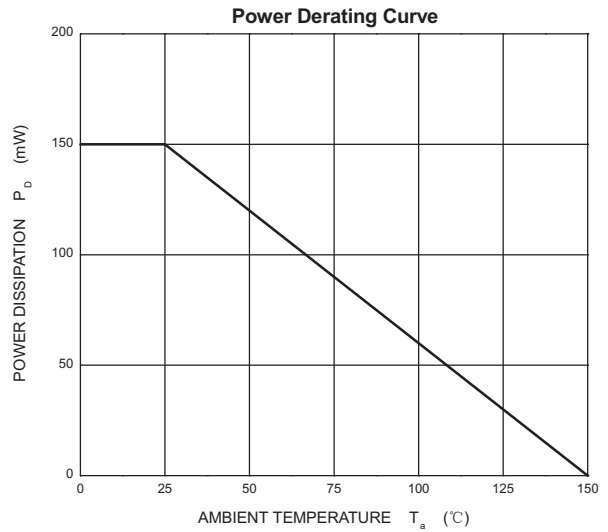
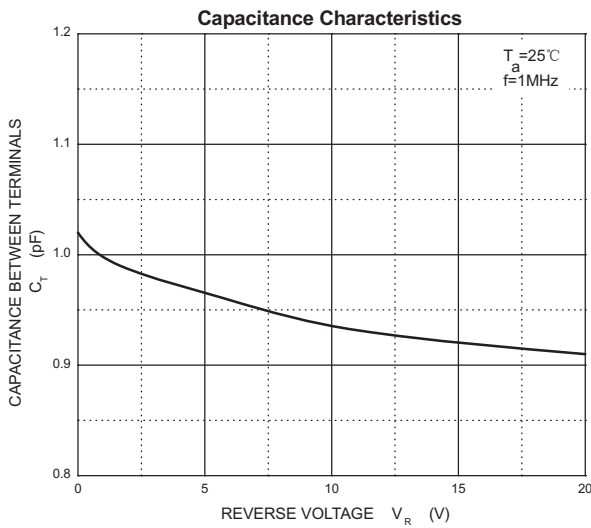
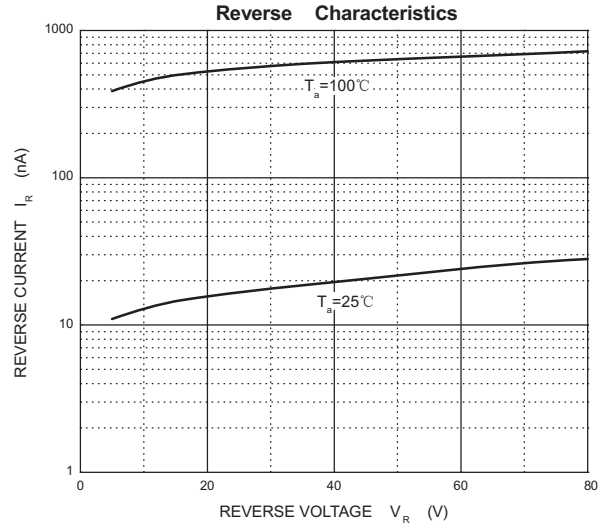
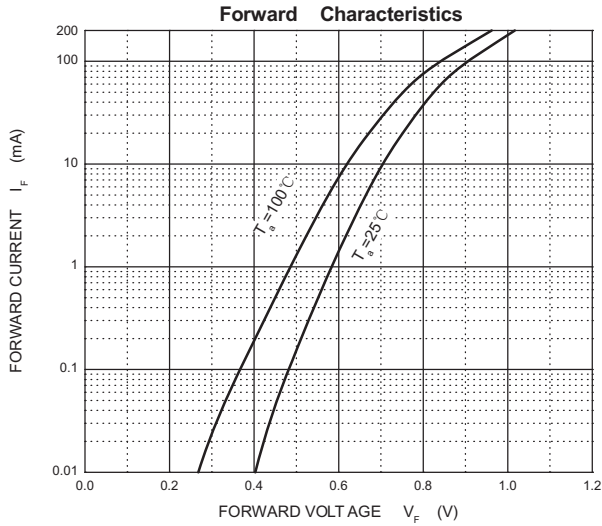
Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	UNIT
Non-repetitive peak reverse voltage	V_{RM}	100	V
Reverse voltage	V_R	75	V
Peak repetitive reverse voltage	V_{RRM}		
Working peak reverse voltage	V_{RWM}		
RMS reverse voltage	V_{RMS}	53	V
Average rectified output current	I_o	150	mA
Forward continuous current	I_{FM}	300	mA
Non-repetitive peak forward surge current@ $t=8.3\text{ms}$	I_{FSM}	2	A
Power dissipation	P_D	150	mW
Thermal resistance from junction to ambient	$R_{\theta JA}$	833	$^{\circ}\text{C}/\text{W}$
Operating junction temperature range	T_J	-55 to +150	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^{\circ}\text{C}$

Electrical characteristics (at $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Condition	Symbol	MIN.	TYP.	MAX.	UNIT
Reverse breakdown voltage	$I_R=1\mu\text{A}$	V_B	75			V
Reverse leakage current	$V_R=20\text{V}$ $V_R=75\text{V}$	I_R			25 1	nA μA
Forward voltage	$I_F=1\text{mA}$ $I_F=10\text{mA}$ $I_F=50\text{mA}$ $I_F=150\text{mA}$	V_F			0.715 0.855 1.00 1.25	V
Reverse recovery time	$I_F=I_R=10\text{mA}$, $I_{rr}=0.1 \cdot I_R$, $R_L=100\Omega$	t_{rr}			4.0	ns
Total capacitance	$V_R=0\text{V}$, $f=1\text{MHz}$	C_T			2.0	pF

Rating and characteristic curves



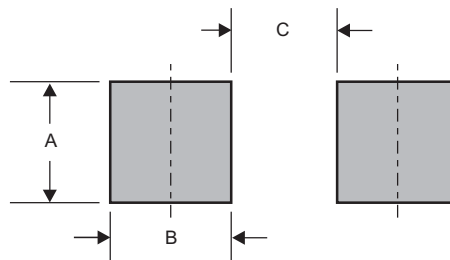
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
1N4148WT	E1 or T4

Suggested solder pad layout



Dimensions in inches and (millimeters)

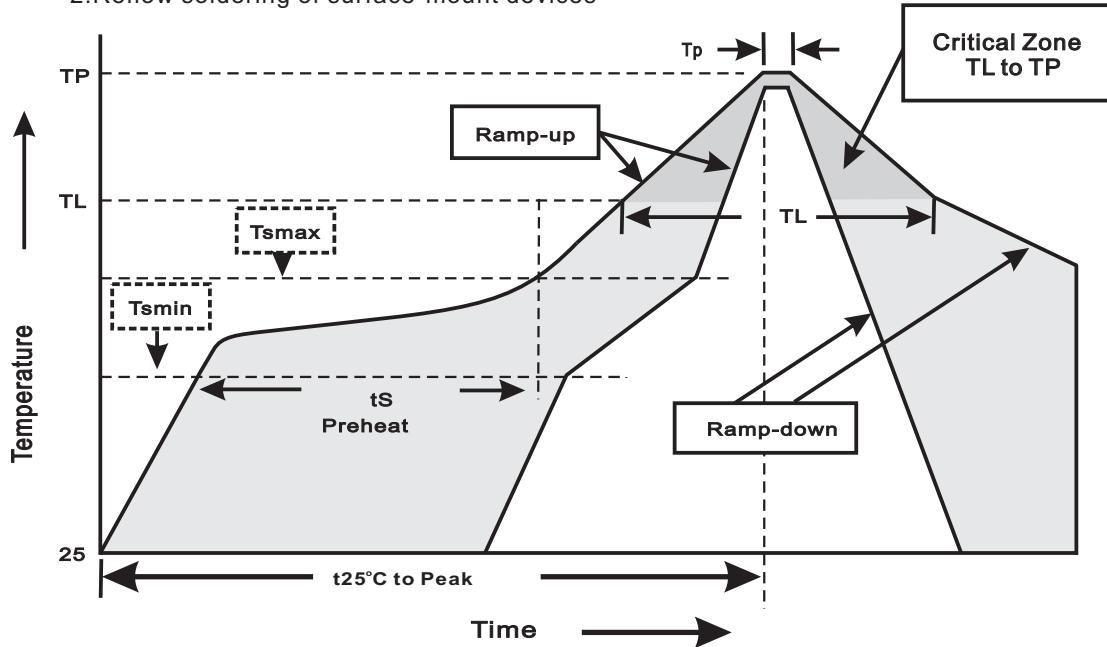
PACKAGE	A	B	C
SOD-523	0.032 (0.80)	0.024 (0.60)	0.044 (1.10)

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-523	7"	8,000	2.0	80,000	183*123*183	178	382*257*387	640,000	9.5

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smin}) -Temperature Max(T _{smax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes